



Silicon Nitride Forming Roller

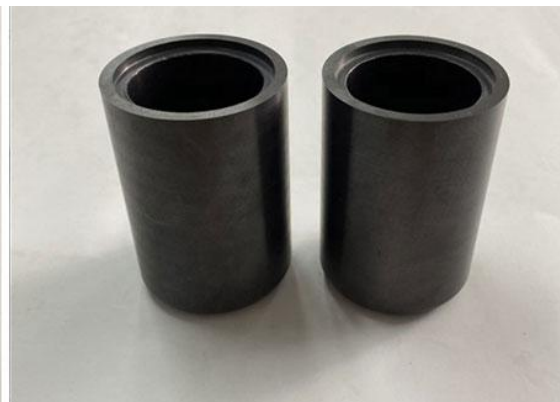
Silicon nitride forming rollers have already been applied in roll forming machines which allow complex variable sections to be manufactured. Si₃N₄ Forming Rollers for plastic forming result in lower metal adhesion to the rollers, enhancing product quality. Nextgen Advanced Materials supplies the Silicon Nitride Forming Rollers with high quality and fast delivery. Meanwhile, the

customization is available.

Product Description

Buy Silicon Nitride Forming Roller which is of high quality directly with low price. Nextgen Advanced Materials INC regards quality as the life of the enterprise, strictly manages quality and actively participates in market competition, with remarkable performance, receiving support from domestic customers, while actively exploring the international market, exporting products to the Philippines, Pakistan, Australia, New Zealand, Venezuela, India, Japan, the Netherlands, the United States and other countries, the quality of products has been widely praised and has left a good impression on customers.

Silicon nitride forming roller is a man-made composite product synthesized through several different chemical reaction methods. Due to the even performance in high temperature, Si₃N₄ ceramic is a commonly used ceramic material in the metallurgical industry. It has excellent thermal shock resistance due to the microstructure. The creep and oxidation resistance of Si₃N₄ is also superior, its low thermal conductivity and high wear resistance also make it an outstanding material that can withstand conditions of most industrial applications.



Specification

Color	Grey
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Mechanical Properties	
Density	3.21 g/cm ³
Compressive Strength	3000 MPa
Flexural Strength	800 MPa
Weibull-Modulus m	15
Fracture Toughness K _{Ic}	6.5 MPa m ^{1/2}
Young's Modulus E	320 GPa
Poisson Ratio	0.28
Hardness Vickers (HV 1)	16 GPa
Thermal Properties	
Maximum Temperature (Inert Gas)	1200°C
Maximum Temperature (Air)	1100°C
Thermal Conductivity @ 20°C	28 W/mK
Thermal Conductivity @ 1000°C	16 W/mK
Thermal Expansion (20–100°C)	2*10 ⁻⁶ /K
Thermal Expansion (20–1000°C)	3.510-6/K
Thermal Shock parameter R1	600 K
Thermal Shock parameter R2	15 W/mm
Electrical Properties	
Resistivity at 20°C	10 ¹² Ωcm
Resistivity at 800°C	10 ⁷ Ωcm
Dielectric constant	6 MHz